

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc2630hsc6-lz10#trpbf

(Engineering Calculation)

SC70

(printed on: 2020-07-11 21:57:22)

TOTAL MASS (g) : 0.010074

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|---------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.000407 | 1000000 | 40400.5546875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.003159 | 975000 | 313575.78125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000078 | 24000 | 7742.61181641 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000001 | 300 | 99.264251709 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000002 | 700 | 198.528503418 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.003240 | 1000000 | 321616.1875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.003408 | 1000000 | 338304.46875 | | |
| | | External Plating Total: | | | | 0.003408 | 1000000 | 338304.46875 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000023 | 1000000 | 2283.07788086 | | |
| Internal Plating Total: | | | | 0.000023 | 1000000 | 2283.07788086 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000258 | 750000 | 25610.1757812 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000086 | 250000 | 8536.7265625 | | |
| Die Attach Total: | | | | 0.000344 | 1000000 | 34146.90625 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.000151 | 58000 | 14988.9023438 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.002314 | 890000 | 229697.484375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000130 | 50000 | 12904.3525391 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000005 | 2000 | 496.321228027 | | |
| | | Encapsulation Total: | | | | 0.002600 | 1000000 | 258087.0625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000052 | 1000000 | 5161.74121094 | | |
| | | | | | TOTAL MASS (g) : | 0.010074 | | |